CERN Technical Training 2005



Electronics in High Energy Physics Winter Term: Introduction to Electronics in HEP

Printed Circuit Boards (PCB) and Hybrids: Part 1 Design and Assembly

> Betty Magnin / TS-DEM 3 February 2005

From schematic to assembly

A 3-step process



- 1. Design steps
- 2. Tools
- 3. Good practice

1. Design steps

- Select and create components
- Capture schematics
- Define mechanical layout
- Place components
- Define PCB stackup
- Routing
- Autorouting
- Post routing issues
- Create manufacturing and assembly documents

Select and create components

- Search into libraries
- Select according to electrical requirements
- Select component package (PTH/SMD, QFP/BGA, ...)
- Create new components (standardize)

Capture schematics

- Use hierarchical structure (pages, blocks)
- Insert all components (decoupling caps, safety components,..)
- Trace bus and interconnections
- Arrange the presentation
- Verify (NC, all 0V, grounds and power supplies, ...)

Define mechanical layout

- Specific or standard formats (3U, 6U, 9U...)
- Mechanical requirements (fixing holes, cooling, ...)
- Position of components on the front panel

Place components

- Electrical constraints (Impedance, EMC, RF, ...)
- Mechanical constraints (limited height, cooling...)
- Assembly process (PTH/SMD, top, bottom, clearance for machines,...)

Determine the PCB layer stackup

- Even number of copper layers
- Symmetrical stackup
- Voltage planes next to ground planes to form embedded capacitors
- Impedance requirements

PCB Routing

- Electrical requirements (line spacing and width, impedance, ...)
- Iterative process between placing and routing
- Consider manufacturing capabilities
- Add test pads (for automatic test fixture)

Autorouting

- Saves time for simple designs or simple parts of complex designs
- Routes according to specified parameters
- Not always optimum in terms of PCB manufacturing cost and efficiency (increases number of vias and density of lines)
- Suited for small quantities

Post routing issues

- Add identification (part name, number, revision, ...)
- Analyze the layout for potential signal integrity problems
- Add copper surfaces to equalize copper density
- Use CAD control tools to verify (minimum line spacing, shorts or not connected, ...)

Create specification for manufacturing and assembly

- Generate Gerber files for layers, use Extended Gerber (embedded apertures) format
- Generate drilling files
- Specify stackup and impedance controlled layers, laminate, marking, solder mask, finish required, hole plating requirements
- Create BOM and placing files for assembly
- Create a panel drawing (several PCB's on one panel)

2. Tools

- Design
- Documentation for assembly
- Archiving

Design

- PCAD, CADENCE : maintained at CERN (training, support by IT and design office, centralized CERN library, ...)
- MENTOR, PROTEL, Express PCB, Eagle, WinqCAD, Target 3AD, PCB123, CAD Design,...

Documentation for assembly

Fabmaster

Import CAD and BOM Import design data from more than 65 CAD tools; the most processors in the industry today.

Define Programs for Test Machines

Generate programs for more than 75 multi-vendor test machines; the most available in the industry today.

Shop Floor Documentation

Automatically create electronics assembly process instructions and shop floor documentation, with automatic ECO updates.



eMServer - Supporting manufacturing applications and information throughout the process



Define Assembly Sequences and Program SMT Lines Generate programs for more than 150 SMT machines; the most outputs in the industry today.



Repair Process Intelligent graphics and easy-to-use interfaces for logging defect data, and Hot Spot functionality allowing users to concentrate on areas where defects are more likely.



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Archiving EDMS

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		EDA-00879-V1_mfg <u>zip</u> (419 кь) <u>pdf</u> (1 мь)		
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3. Good practice

- Clearly specify all requirements before starting a layout: do it right the first time, rather than adding continuous changes will save time and problems (use check-lists and design reviews)
- Comply with manufacturing and assembly design rules when designing libraries and layout: fiducials, locating holes, minimum panel size, pads for wave soldering, distance around a component for inspection and repair, ...

3. Good practice

- Keep in touch with progress in technologies: Pb-free will have an influence on a layout !
- Comply with known standards: IPC working groups have already done the job
- Use all possible tools to verify each step (Cadence : Checkplus, ..)
- Provide a clear and complete job to manufacturing and assembly: they cannot guess what you expect if you do not tell them (write instead of say)

From schematic to assembly

A 3-step process



- Components
- Variants of layouts
- Assembly steps
- Assembly process: automatic or manual
- Conditions for quality

Components

- Through hole (PTH, Trad, ...)
- Surface mount (SMD, CMS, ...)
- Packaging : row, tape and reels, sticks, trays

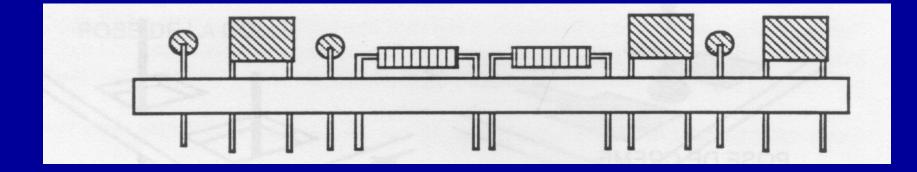




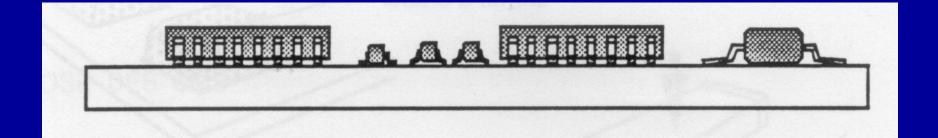
Layout

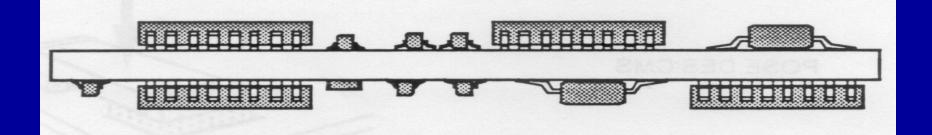
- Components may be placed on several manners
- Each will have an influence on the process to be used

Through hole



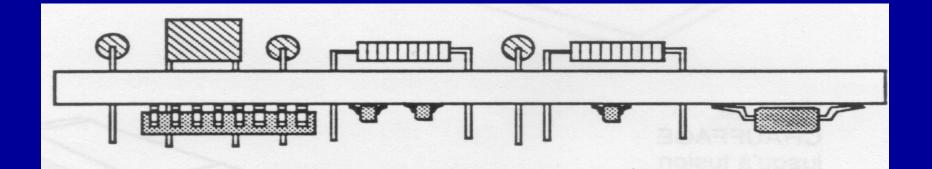
SMD, single side or both sides



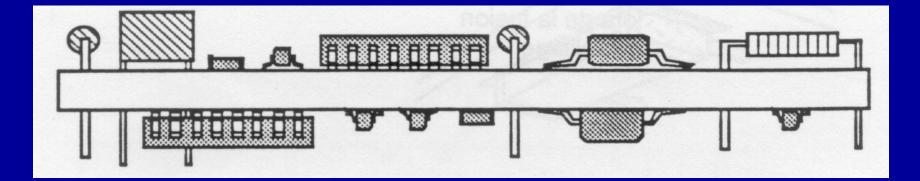


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Trad + SMD-bottom



Trad + SMD-top + SMD-bottom



Assembly steps

- Prepare components
- Mount
- Solder
- Clean
- Inspect
- Repair

Assembly processes

- 100% machine
- 100% manual
- Mixed (used at CERN)

100% machine

- Process for series (>30 pieces)
- Manufacturing price is important for large quantities
- Components on tapes and reels or trays
- Board design must respect design rules (solder pads, fiducials, board sizes, spacing around components, ...)

Screen printing of solder paste

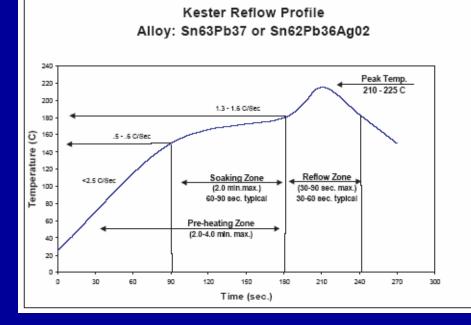


Placement of SMD components



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Reflow soldering: convection, IR, vapor phase



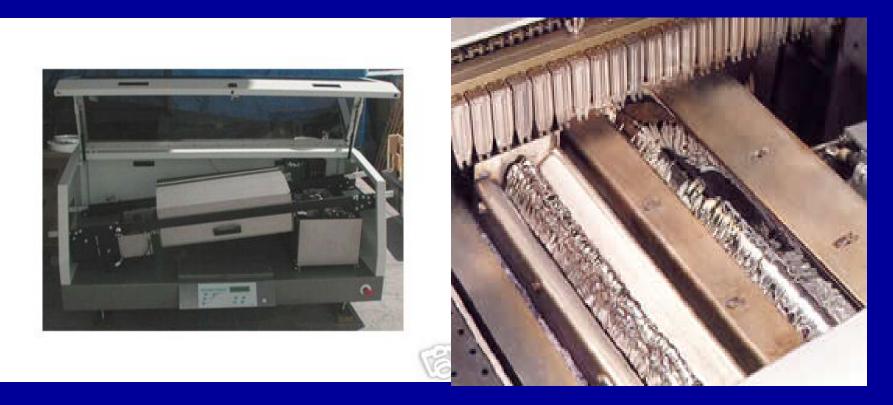


Insertion of through hole components, automatic or manual



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Wave soldering



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Inspection AOI



Test: In-Circuit, flying probe, dedicated functional



Manual or semi-manual process

- Process for prototypes or small series
- Handling of bulk components or parts of tapes is possible, but not preferable (risk in handling and placement of polarized components, ...)
- May use parts of automatic process (i.e.: placement of 100 coupling caps on 3 boards, reflow soldering, ...)
- Board design must respect design rules (SMD pads, free space around components, fiducial for solder paste dispensing or machine placement, ...)
- Expensive process

Solder paste dispensing



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Placement



Hand soldering



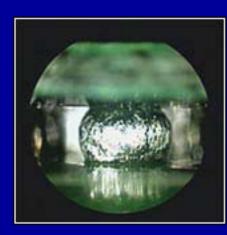
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Visual inspection



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Repair

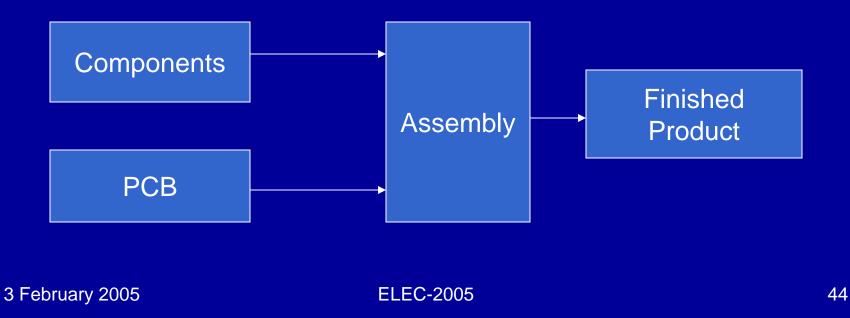




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Conditions for quality

- Quality of assembly process
- Quality of components
- Quality of design



Quality of assembly process

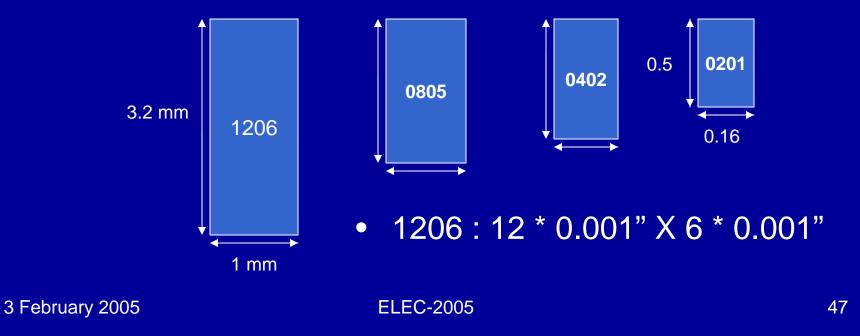
- Machines and processes understood and under control
- Trained operators
- Repetitive results
- Cleanliness is mandatory for reliability

Quality of components

- Protect from
 - Humidity
 - Static discharge
 - Mechanical damage (bent pins)
 - Oxidation
- Allow automatic handling
 - Even for manual process

Quality of components

- PCB is the most important component
- Adapted to controlled process



Quality of design

- Designer's functional requirements
- Manufacturing requirements
- Assembly requirements
- Compliance with tested standards (IPC)
- In phase with current technologies (lead-free)

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